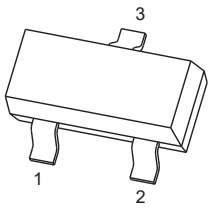
TKMN3406

30V N-Channel MOSFET

Product Summary

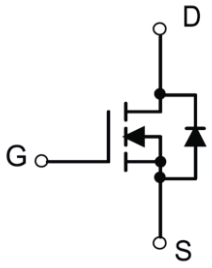
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
30V	37mΩ@10V	3.3A
	47mΩ@4.5V	

SOT-23



1. GATE
2. SOURCE
3. DRAIN

Schematic diagram



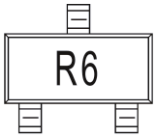
Feature

- TrenchFET Power MOSFET
- Excellent $R_{DS(on)}$ and Low Gate Charge

Application

- DC/DC Converter
- Load Switch for Portable Devices
- Battery Switch

MARKING:



ABSOLUTE MAXIMUM RATINGS (T_a=25℃ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain - Source Voltage		V_{DS}	30	V
Gate - Source Voltage		V_{GS}	±20	V
Continuous Drain Current[1,5]	T_A = 25℃	I_D	3.3	A
Pulsed Drain Current[2]		I_{DM}	14	A
Power Dissipation[4,5]	T_A = 25℃	P_D	1.5	W
Thermal Resistance from Junction to Ambient[5]		$R_{\theta JA}$	83.3	℃/W
Junction and Storage Temperature Range		T_J,T_{STG}	-55~ +150	℃

MOSFET ELECTRICAL CHARACTERISTICS(T_a=25℃ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D =250μA	30			V
Zero gate voltage drain current	I_{DSS}	V_{DS} =24V,V_{GS} = 0V			1	μA
Gate-body leakage current	I_{GSS}	V_{GS} =±20V, V_{DS} = 0V			±100	nA
Gate threshold voltage	$V_{GS(th)}$	V_{DS} =V_{GS}, I_D =250μA	1	1.6	3	V
Drain-source on-resistance[3]	$R_{DS(on)}$	V_{GS} =10V, I_D =3.3A		37	65	mΩ
		V_{GS} =4.5V, I_D =2.8A		47	105	
Forward tranconductance[3]	g_{FS}	V_{DS} =5V, I_D =3.3A	3			S
Body Diode Voltage[3]	V_{SD}	I_S=1A			1	V
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	V_{DS} =15V,V_{GS} =0V,f=1MHz			375	pF
Output Capacitance	C_{oss}			57		
Reverse Transfer Capacitance	C_{rss}			39		
Gate resistance	R_g	V_{DS} =0V,V_{GS} =0V,f =1MHz			6	Ω
SWITCHING CHARACTERISTICS						
Turn-on delay time	$t_{d(on)}$	V_{GS}=10V,V_{DS}=15V, R_L=2.2Ω,R_{GEN}=3Ω		4.6		ns
Turn-on rise time	t_r			1.9		
Turn-off delay time	$t_{d(off)}$			20.1		
Turn-off fall time	t_f			2.6		

Notes :

1.The maximum current rating is limited by package.

2.Pulse Test : Pulse Width ≤ 10μs, duty cycle ≤ 1%.

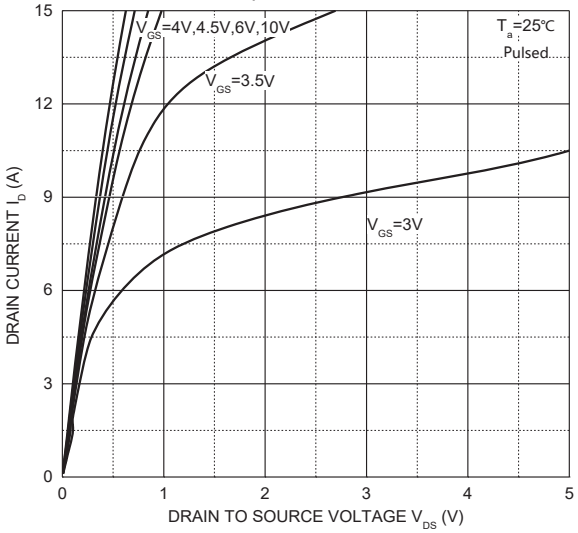
3.Pulse Test : Pulse Width ≤ 300μs, duty cycle ≤ 2%.

4.The power dissipation P_D is limited by $T_{J(MAX)}$ = 150°C.

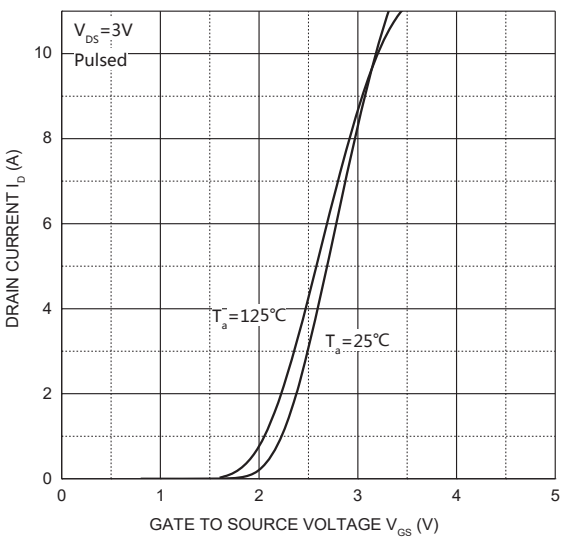
5.Device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.

Typical Electrical and Thermal Characteristics

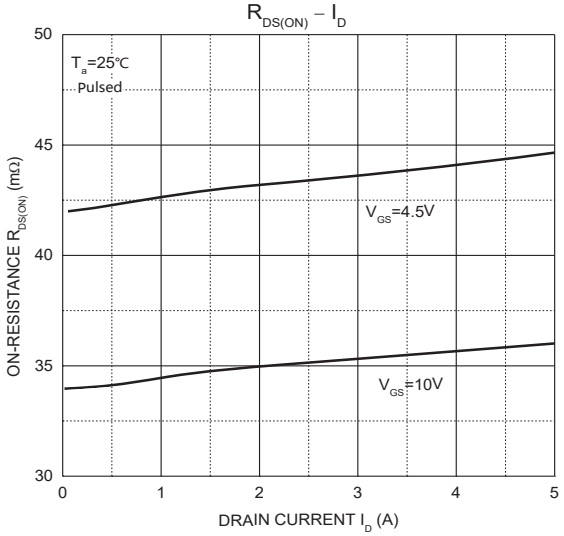
Output Characteristics



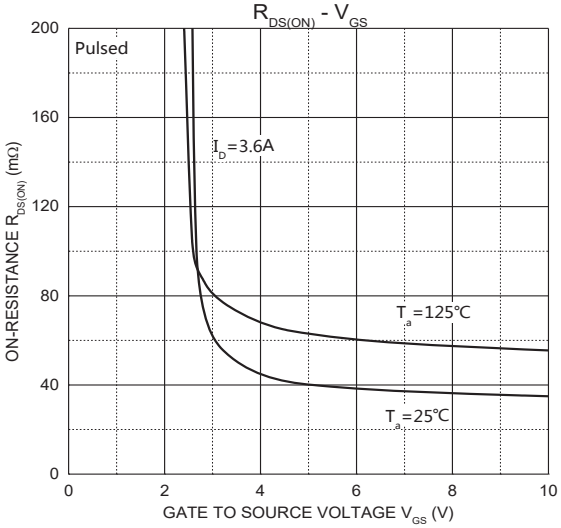
Transfer Characteristics



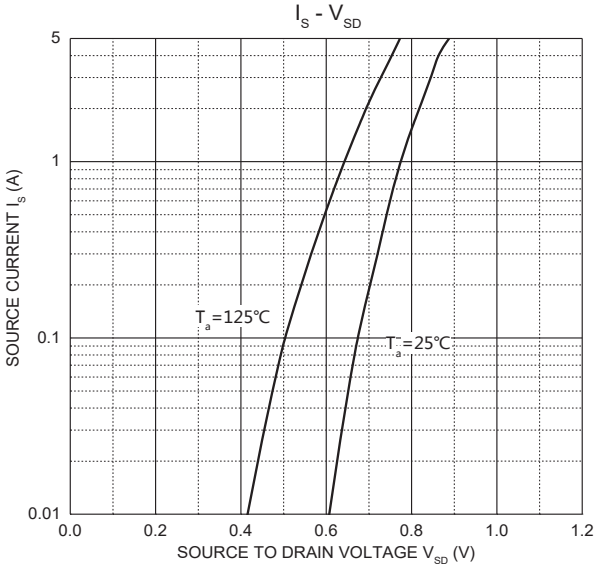
$R_{DS(ON)}$ – I_D



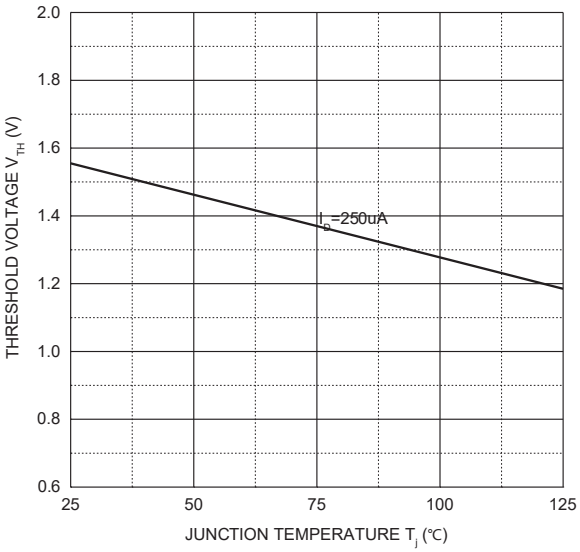
$R_{DS(ON)}$ - V_{GS}

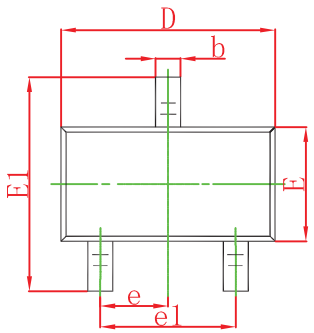


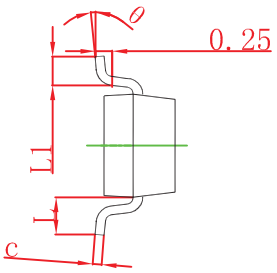
I_S - V_{SD}

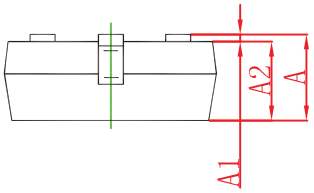


Threshold Voltage



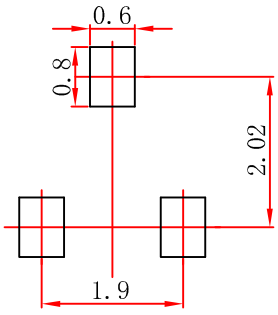






Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.